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		THE DRIVENITOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR		7074	
09/689,824	10/13/2000	Takaaki Sasaki	PNET.011D		
JONES VOLENTINE, LLC SUITE 150 12200 SUNRISE VALLEY DRIVE RESTON, VA 20191			EXAMI	EXAMINER	
			BERRY, RENEE R		
			ART UNIT	PAPER NUMBER	
			2818		
			DATE MAILED: 08/14/2000	DATE MAILED: 08/14/2002	

Please find below and/or attached an Office communication concerning this application or proceeding.

Application No. 09/689,824 Applicant(s)

Examiner

Office Action Summary

Art Unit 2818

Sasaki



		Renee berry				
	The MAILING DATE of this communication appears	on the cover sheet with the corr	espondence address			
			i			
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE MONTH(s) FIRST						
THE M	IAILING DATE OF THIS COMMUNICATION. One of time may be available under the provisions of 37 CFR 1.136 (a). In	no event, however, may a reply be timely fil	ed after SIX (6) MONTHS from the			
-noiling	date of this communication.		the considered timely.			
- If the pe	date of this communication. ariod for reply specified above is less than thirty (30) days, a reply within the ariod for reply is specified above, the maximum statutory period will apply a reply is specified above, the maximum statutory period will apply a reply the statute. Cause is	and will expire SIX (6) MONTHS from the ma	alling date of this communication.			
- Failure 1	ariod for reply is specified above, the maximum statutory period will apply to reply within the set or extended period for reply will, by statute, cause to any received by the Office later than three months after the mailing date of	this communication, even if timely filed, may	reduce any			
- Any rep earned	patent term adjustment. See 37 CFR 1.704(b).					
Status	territor (a) filed on May 21	2002	·			
1) 💢	Responsive to communication(s) filed on <u>May 21,</u>	ction is non-final.				
2a) 🗌			secution as to the merits is			
3) 🗆	3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11; 453 O.G. 213.					
Disposit	tion of Claims	is/	are pending in the application.			
4) 💢	Claim(s) <u>7-15</u>		to position from consideration			
4	la) Of the above, claim(s)	IS	is/are allowed			
5) 💢	Claim(s) <u>7-15</u>		is/are rejected.			
6) 🗆	Claim(s)		is/are objected to			
7) 🗆	Claim(s)		is/are objected to.			
8) 🗆	Claims	are subject to res	triction and/or election requirements			
Applica	ation Papers					
9) 🗆	The specification is objected to by the Examiner.		the burthe Eveniner			
10)□	is/are a) accepted or b) before to by the Examiner.					
		drawing(s) he held in abeyance.	See 37 CFN 1.03(a).			
11)□	The proposed drawing correction filed on	is: a) □ approv	red b) disapproved by the Examiner			
	If approved, corrected drawings are required in rep	ly to this Office action.				
12)	The oath or declaration is objected to by the Exa	miner.				
Priorit			Q(a) (d) or (f)			
13)□		priority under 35 U.S.C. 9 11	9(4)-(0) 01 (1).			
a)	☐ All b)☐ Some* c)☐ None of:					
	1. Certified copies of the priority documents i	have been received.	an Ma			
	2. Certified copies of the priority documents i	nave been received in Applicati	on No			
	Copies of the certified copies of the priority application from the International B					
*	See the attached detailed Office action for a list of	tue certified cobies not receive	119(e)			
14)[Acknowledgement is made of a claim for domes	and application has been recei	ved.			
a)	The translation of the foreign language provisi	onal application has been received a priority under 35 U.S.C. §§	3 120 and/or 121.			
15)	Acknowledgement is made of a claim for dome:	suc priority dilect do dicio. St				
	nment(s)	4) Interview Summary (PTO-413)	Paper No(s).			
	Notice of References Cited (PTO-892)	5) Notice of Informal Patent Appli				
	2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 5) Notice of Informal Patent Application (PTO-949) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s).					
ı 3)l	Information Disclosure Statement, 1					

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless --

- (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371© of this title before the invention thereof by the applicant for patent.
- 2. Claims 7-15 are rejected under 35 U.S.C. 102(e) as being anticipated by US patent no. 5,866,942 to Suzuki et al.

Suzuki teaches a method of making a semiconductor package comprising preparing a semiconductor package structure by providing a substrate for mounting a semiconductor element thereon to fix a semiconductor element to one side thereof and a connecting pattern provide on the other side of the substrate and by forming a through hole from the one side to the other side of the substrate; fixing a surface where the element is formed of a semiconductor element on the one side of the substrate of the semiconductor package such that an electrode of the semiconductor element is within the through hole; electrically connecting a connecting pattern and an electrode of a semiconductor element via wires through the through hole; and sealing the through hole and wires with resin at column 12, lines 56-67, claim 1.

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In regard to claim 8, Suzuki teaches a connecting pattern is provided continuously in a plurality of stages and an end portion of connecting pattern on the side of the through hole is provided on a stage on the side of the one side of the substrate at column 13, lines 28-46, claim 8.

In regard to claim 9, Suzuki teaches the through hole is a plurality of through holes at column 12, lines 56-67.

In regard to claim 10, Suzuki teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate of the semiconductor package via a tape-like bonding material at column 14, lines 35-37, claim 14.

In regard to claim 11, Suzuki teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate of the semiconductor package with adhesive at column 14, lines35-37.

In regard to claim 12, Suzuki teaches the surface where the element is formed of the semiconductor element is fixed on the one side of the substrate semiconductor package via a tapelike bonding material at column 14, lines 35-37.

In regard to claim 13, Suzuki teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate semiconductor package via a tapelike bonding material at column 14, lines 35-39.

In regard to claim 14, Suzuki teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate of semiconductor package with adhesive at column 14, lines 35-37.

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In regard to claim 15, Suzuki teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate of the semiconductor package with adhesive at column 14, lines 35-37.

Conclusion

3. Any inquiry concerning this communication or earlier communications from the examiner should be directed to R. R. Berry whose telephone number is (703) 305-4544.

HOAIHO PRIMARY EXAMINER

AMY RRB

August 12, 2002